

CHIP COMMON MODE CHOKES FASCCM0608,1210CE SERIES



FEATURES :

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission

APPLICATIONS:

MIPI, MHL serial interface in mobile device

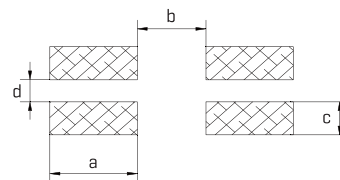
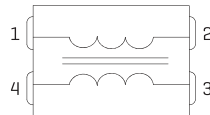
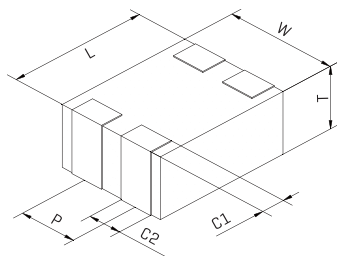
GENERAL SPECIFICATIONS:

Rated current:0.13A to 0.16A
Parameters Test Temp:25°C
Test Frequency:100MHz
Operating temperature:-20°C to +85°C
Storage Temp:-0°C to +40°C
Resistance to Soldering Heat:260°C for 10 sec
Temperature Rise:40°C Typ. at Rated Current
All parts meet ROHS compliance

ELECTRICAL CHARACTERISTICS

Part Number	Impedance [ohm]±25%	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Withstand Voltage [V]	Part Number	Impedance [ohm]±25% Common Mode	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Impedance [ohm]Max Differential Mode
FASCCM0608-650	65	2.5	130	5.0	25	FASCCM1210CE-900	90	1.75	160	5.0	15
FASCCM0608-900	90	2.5	130	5.0	25	FASCCM1210CE-121	120	2.20	140	5.0	18
						FASCCM1210CE-201	200	2.70	130	5.0	20

TECHNICAL INFORMATION:



PAD LAYOUT:

DIMENSIONS:MM

Part number	L	W	T	P	C1	C2	a	b	c	d
FASCCM0608	0.65±0.05	0.85±0.05	0.45±0.05	0.50±0.1	0.10 Min	0.27±0.1	0.30 REF	0.30 REF	0.30 REF	0.20 REF
FASCCM1210CE	1.25±0.2	1.00±0.2	0.50±0.2	0.55±0.2	0.20±0.15	0.30±0.2	0.70 REF	0.55 REF	0.30 REF	0.20 REF

CHIP COMMON MODE CHOKES FASCCM1210&1210HS SERIES



FEATURES:

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS. without distortion to high speed signal transmission.

APPLICATIONS:

MIPI, MHL serial interface in mobile device.

GENERAL SPECIFICATIONS:

Rated current:0.1A to 0.3A.
Parameters Test Temp:20°C.
Test Frequency:100MHz.
Operating temperature:-20°C to +85°C.
Storage Temp:-0°C to +40°C.
Resistance to Soldering Heat:260°C for 10 sec.
Temperature Rise:40°C Typ. at Rated Current.
All parts meet ROHS compliance.

ELECTRICAL CHARACTERISTICS

Part Number	Impedance [Ω] $\pm 25\%$	D.C.R [Ω]Max at 20°C	Rated current [mA]Max	Rated Voltage [V]	Insulation Resistance [M Ω]Min	Part Number	Impedance [Ω] $\pm 25\%$ Common Mode	D.C.R [Ω]Max at 20°C	Rated current [mA]Max	Rated Voltage [V]	Insulation Resistance [M Ω]Min
FASCCM1210-360	36	0.50	300	10	200	FASCCM1210HSH-900A	90	1.0	100	10	100
FASCCM1210-670	67	0.50	300	10	200	FASCCM1210HSD-500A	50	1.5	100	10	100
FASCCM1210-900	90	0.60	300	10	200	FASCCM1210HSD-670A	67	1.5	100	10	100
FASCCM1210-121	120	0.60	300	10	200	FASCCM1210HSD-900A	90	1.5	100	10	100
						FASCCM1210HSD-900B	90	3.0	100	10	100
						FASCCM1210HSS-150A	15	0.8	100	10	100

TECHNICAL INFORMATION:

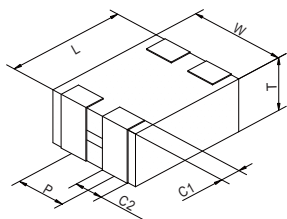


FIG1.

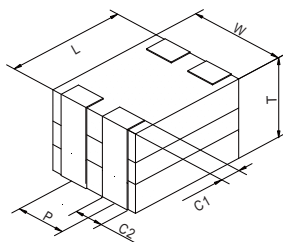
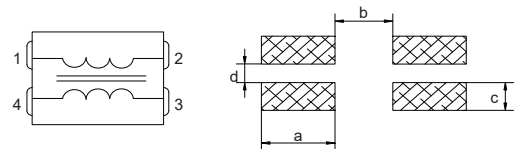


FIG2.

PAD LAYOUT:



DIMENSIONS:MM

Part number	L	W	T	P	C1	C2	a	b	c	d	FIG
FASCCM1210	1.25 \pm 0.2	1.00 \pm 0.2	0.60 \pm 0.2	0.50 \pm 0.2	0.20 \pm 0.15	0.30 \pm 0.2	0.70 REF	0.55 REF	0.30 REF	0.20 REF	1
FASCCM1210HS	1.25 \pm 0.2	1.00 \pm 0.2	0.50 \pm 0.2	0.55 \pm 0.2	0.20 \pm 0.15	0.30 \pm 0.2	0.50 REF	0.75 REF	0.30 REF	0.2 REF	2

CHIP COMMON MODE CHOKES FASCCM2012,2012HS SERIES



FEATURES :

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission

APPLICATIONS:

MIPI, MHL serial interface in mobile device

GENERAL SPECIFICATIONS:

Rated current:0.1A to 0.5A
Parameters Test Temp:25°C
Test Frequency:100MHz
Operating temperature:-20°C to +85°C
Storage Temp:-0°C to +40°C
Resistance to Soldering Heat:260°C for 10 sec
Temperature Rise:40°C Typ. at Rated Current
All parts meet ROHS compliance

ELECTRICAL CHARACTERISTICS

Part Number	Impedance [ohm]±25%	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Withstand Voltage [V]	Part Number	Impedance [ohm]±25% Common Mode	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Impedance [ohm]Max Differential Mode
FASCCM2012-670	67	0.40	400	10	200	FASCCM2012HSH-670A	67	1.0	200	10	100
FASCCM2012-900	90	0.40	400	10	200	FASCCM2012HSH-900A	90	1.0	200	10	100
FASCCM2012-121	120	0.40	400	10	200	FASCCM2012HSD-500A	50	1.0	100	10	100
FASCCM2012-161	160	0.50	400	10	200	FASCCM2012HSD-900A	90	1.0	200	10	100
FASCCM2012-181	180	0.50	400	10	200	FASCCM2012HSD-121A	120	1.2	100	10	100
FASCCM2012-221	220	0.50	300	10	200	FASCCM2012HSS-500A	50	1.0	100	10	100

TECHNICAL INFORMATION AND PAD LAYOUT:

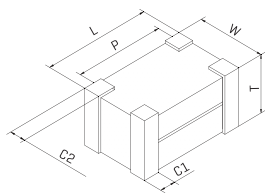


FIG1.

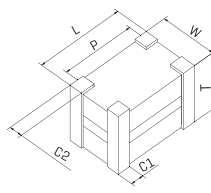
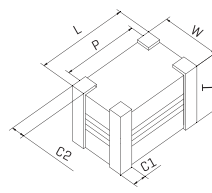
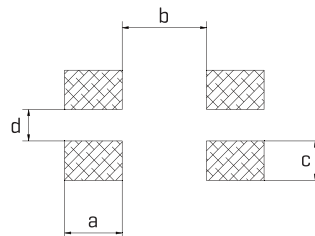
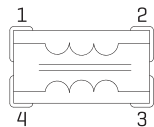


FIG2.



FASCCM2012HSS-500A FIG2.



DIMENSIONS:MM

Part number	L	W	T	P	C1	C2	a	b	c	d	FIG
FASCCM2012	2.00±0.2	1.25±0.2	1.00±0.1	1.60±0.2	0.40±0.2	0.30±0.2	0.75 REF	1.10 REF	0.50 REF	0.40 REF	1
FASCCM2012HS	2.00±0.2	1.20±0.2	1.00±0.2	1.60±0.2	0.40±0.2	0.30±0.2	0.75 REF	1.10 REF	0.50 REF	0.4 REF	2

CHIP COMMON MODE CHOKES FASCCM3216 SERIES



FEATURES:

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission

APPLICATIONS:

MIPI, MHL serial interface in mobile device

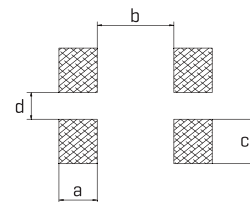
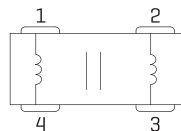
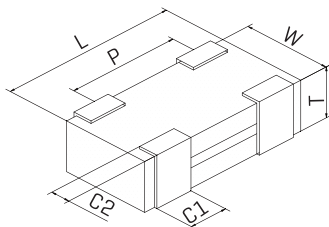
GENERAL SPECIFICATIONS:

Rated current:0.5A
Parameters Test Temp:25°C
Test Frequency:100MHz
Operating temperature:-20°C to +85°C
Storage Temp:-0°C to +40°C
Resistance to Soldering Heat:260°C for 10 sec
Temperature Rise:40°C Typ. at Rated Current
All parts meet ROHS compliance

ELECTRICAL CHARACTERISTICS

Part Number	Impedance [ohm]±25%	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Withstand Voltage [V]	Insulation Resistance [Mohm]Min
FASCCM3216-900	90	0.50	500	10	25	200
FASCCM3216-121	120	0.50	500	10	25	200

TECHNICAL INFORMATION AND PAD LAYOUT:



DIMENSIONS:MM

Part number	L	W	T	P	C1	C2	a	b	c	d
FASCCM3216	3.20±0.2	1.60±0.2	1.00±0.1	2.10±0.2	0.70±0.2	0.30±0.2	0.70 REF	1.40 REF	1.00 REF	0.60 REF